

IN THE CLAIMS

✓  
Please cancel without prejudice claims 1-6. ✓✓

7. (Amended) [The heat exchanger of claim 1 wherein the at least one heat transfer mechanism comprises:] A heat exchanger comprising  
a first heat dissipation mechanism having a first heat dissipation capacity;  
a second heat dissipation mechanism having a second heat dissipation capacity;  
a variable thermal conductivity heat pipe having a first portion thermally coupled to  
[the] <sup>NS (405)</sup> <sup>405</sup> a heat generating component, <sup>405</sup> a second portion thermally coupled to the first  
heat dissipation mechanism, <sup>430</sup> <sup>415</sup> and a third portion separated from the first portion  
and the second portion by [the] <sup>410</sup> <sup>410</sup> a limited conductivity portion and thermally  
coupled to the second heat dissipation mechanism. <sup>430</sup>

8. (Amended) The heat exchanger of claim [1]7 wherein the [at least one heat transfer mechanism]variable thermal conductivity heat pipe has a first thermal path with a first thermal conductivity which couples the heat generating component to the first heat dissipation mechanism and has a second thermal path with a second thermal conductivity which couples the heat generating component to the second heat dissipation mechanism and wherein the first thermal conductivity is at least twice the second thermal conductivity and the first heat dissipation mechanism is an active heat dissipation mechanism.

9. (Amended) The heat exchanger of claim [8]7 wherein the heat generating component is a processor and wherein <sup>1/21)</sup>the second thermal conductivity is approximately four times <sup>1/21)</sup>the first thermal conductivity

10. (Amended) The heat exchanger of claim [8]7 wherein the <sup>1/21)</sup>first heat dissipation mechanism is an active heat dissipation mechanism that is enabled depending on at least the temperature of the heat generating component.

11. (Amended) The heat exchanger of claim [1]7 wherein the first heat dissipation mechanism is a fan based heat exchanger and wherein the second heat dissipation mechanism is a thermally conductive plate beneath and substantially parallel to a keyboard.

✓  
Please cancel without prejudice claims 13-16. ✓ ✓ ✓

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Please cancel without prejudice claims 22-26. ✓ ✓ ✓

27. (New) An apparatus comprising:

<sup>205</sup>  
at least one electronic component;

<sup>400</sup> a heat pipe having a limited conductivity <sup>410</sup> portion, the heat pipe having a <sup>405</sup> first portion

<sup>205</sup>  
thermally coupled to the at least one electronic component;

a fan based heat exchanger thermally coupled to a second portion of the heat pipe;

<sup>430</sup> a metallic plate coupled to a third <sup>415</sup> portion of the heat pipe and separated from the first

portion that is connected to the at least one electronic component by the limited

<sup>410</sup>  
conductivity portion of the heat pipe.

28. (New) The apparatus of claim 27 wherein the metallic plate comprises a plate

<sup>440</sup>  
substantially beneath a keyboard.

29. (New) The apparatus of claim 27 wherein said limited thermal conductivity

portion of said heat pipe comprises a narrowed portion of said heat pipe.

30. (New) The apparatus of claim 28 wherein the metallic plate comprises a portion of

a thermally enhanced keyboard.

### REMARKS

Applicant submits that all claims now pending are in condition for allowance at least by